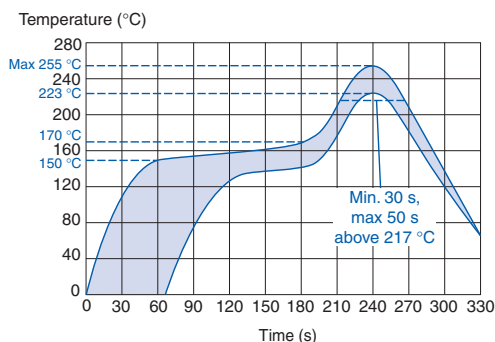


Actual Situation of Lead Free Soldering for SPC

May 28th, 2007

All following SPC7.3 capacitors, with manufacturing code V5 (May 2007) and later, are capable to fulfil the recommended reflow soldering profile for lead free process presented at end of this document.

Capacitance µF	Size code	Dimensions in mm ±0.2		Max dU/dt V/µs	Article code	Capacitance µF	Size code	Dimensions in mm ±0.2		Max dU/dt V/µs	Article code
		B	H					B	H		
100 VDC/ 63 VAC						400 VDC/ 250 VAC					
CHIP LENGTH 7.3 MM CODE 2824						CHIP LENGTH 7.3 MM CODE 2824					
0.00047	K31	6.0	2.5	800	SPC7.3 471K100K31 TR12	0.00047	K31	6.0	2.5	1600	SPC7.3 471K400K31 TR12
0.00068	K31	6.0	2.5	800	SPC7.3 681K100K31 TR12	0.00068	K31	6.0	2.5	1600	SPC7.3 681K400K31 TR12
0.0010	K31	6.0	2.5	800	SPC7.3 102K100K31 TR12	0.0010	K31	6.0	2.5	1600	SPC7.3 102K400K31 TR12
0.0015	K31	6.0	2.5	800	SPC7.3 152K100K31 TR12	0.0015	K31	6.0	2.5	1600	SPC7.3 152K400K31 TR12
0.0022	K31	6.0	2.5	800	SPC7.3 222K100K31 TR12	0.0022	K31	6.0	2.5	1600	SPC7.3 222K400K31 TR12
0.0033	K31	6.0	2.5	800	SPC7.3 332K100K31 TR12	0.0033	K33	6.0	3.0	1600	SPC7.3 332K400K33 TR12
0.0047	K31	6.0	2.5	800	SPC7.3 472K100K31 TR12	0.0047	K35	6.0	3.5	1600	SPC7.3 472K400K35 TR12
0.0068	K31	6.0	2.5	800	SPC7.3 682K100K31 TR12	0.0068	K37	6.0	4.5	1600	SPC7.3 682K400K37 TR12
0.010	K31	6.0	2.5	800	SPC7.3 103K100K31 TR12						
0.015	K33	6.0	3.0	800	SPC7.3 153K100K33 TR12	630 VDC/ 350 VAC					
0.022	K35	6.0	3.5	800	SPC7.3 223K100K35 TR12	CHIP LENGTH 7.3 MM CODE 2824					
0.033	K37	6.0	4.5	800	SPC7.3 333K100K37 TR12	0.00047	K31	6.0	2.5	2000	SPC7.3 471K630K31 TR12
250 VDC/ 160 VAC						0.00068	K31	6.0	2.5	2000	SPC7.3 681K630K31 TR12
CHIP LENGTH 7.3 MM CODE 2824						0.0010	K31	6.0	2.5	2000	SPC7.3 102K630K31 TR12
0.00047	K31	6.0	2.5	1200	SPC7.3 471K250K31 TR12	0.0015	K31	6.0	2.5	2000	SPC7.3 152K630K31 TR12
0.00068	K31	6.0	2.5	1200	SPC7.3 681K250K31 TR12	0.0022	K33	6.0	3.0	2000	SPC7.3 222K630K33 TR12
0.0010	K31	6.0	2.5	1200	SPC7.3 102K250K31 TR12	0.0033	K35	6.0	3.5	2000	SPC7.3 332K630K35 TR12
0.0015	K31	6.0	2.5	1200	SPC7.3 152K250K31 TR12	0.0047	K37	6.0	4.5	2000	SPC7.3 472K630K37 TR12
0.0022	K31	6.0	2.5	1200	SPC7.3 222K250K31 TR12						
0.0033	K31	6.0	2.5	1200	SPC7.3 332K250K31 TR12						
0.0047	K31	6.0	2.5	1200	SPC7.3 472K250K31 TR12						
0.0068	K33	6.0	3.0	1200	SPC7.3 682K250K33 TR12						
0.010	K35	6.0	3.5	1200	SPC7.3 103K250K35 TR12						
0.015	K37	6.0	4.5	1200	SPC7.3 153K250K37 TR12						



Reflow soldering on the top body surface of the component

Preheating temperature should be less than 170°C. The time above 217°C should be less than 50 s. The peak temperature must not exceed 255°C.

This profile is recommended for convection reflow ovens and IR reflow ovens. If vapour phase reflow oven is used, please consult Evox Rifa.

This recommended reflow soldering profile for lead free soldering is valid for those SPC products listed above, which have manufacturing code V5 (May 2007) and later.

For marking of our SMD capacitors, please see page 18 in the Evox Rifa SMD Film Capacitors catalogue or www.evoxrifa.com/smd_catalog/wound_tech_caps/gen_info_wound_smd.pdf

Exceeding the manufacturer's process recommendations may harm the component and keep the manufacturer not liable for any defect caused by exceeding the recommendations.

According to international standards, the maximum temperature capability shall be measured on the top surface of a component. Any of the international standards do not define how the thermocouple should be fastened on the component. Our recommendation for attaching the thermocouple on the top surface of the component is glueing with high temperature resistant glue.

All updates for SMD capacitors reflow capability will be informed through www.evoxrifa.com.

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